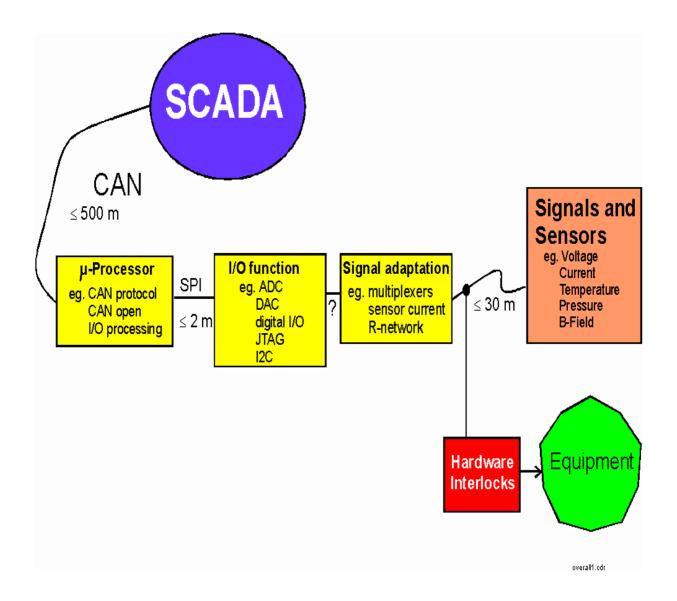
Pixel DCS Status and Issues 2/2001

G. D. Hallewell: RAL/CPPM

Contents

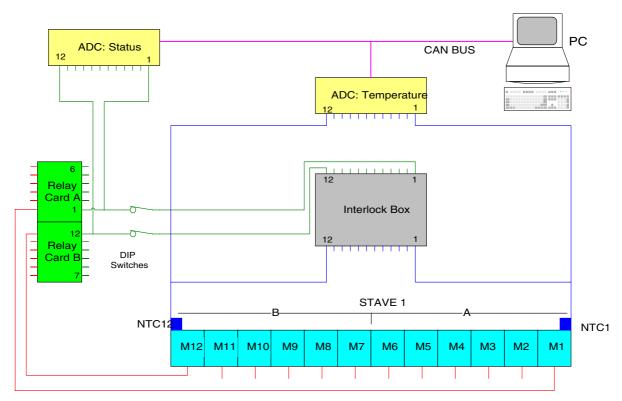
- On-module NTC Temperature sensors & I-boxes (Interlock Boxes) to protect Pixel Modules
- Flow and Pressure Control in the Evaporative Cooling System and Analog Pneumatic Controls Development
- The "Embedded Local Monitor Box (E-LMB) as an acquisition node for slow monitoring.
- Possible Sharing of NTC information with LMBs for independent logging (connectivity issues)
- An Add-On DAC for the E-LMB (Draft Specification)
- Numbers of E-LMBs (and signal adapters) in final system for module temperature, PID flow control & PID tube bundle temperature control
- First Experience with PVSS2 (final SCADA) software.
- Highly Redundant LV UPS for I-Box, controls power
- Where from here/ how to divide the work

Major Elements (Hard & Soft) of the Detector Control System



On-module NTC Temperature sensors & I-boxes (Interlock Boxes) to protect Pixel Modules

Interlock Box Control System



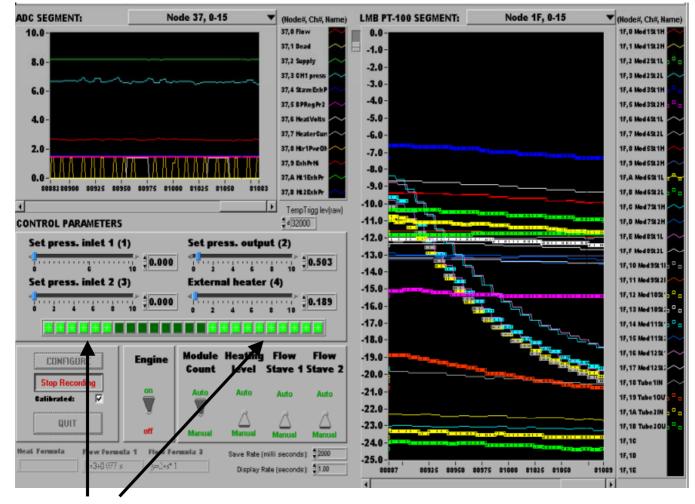
NTC Thermal Sensors glued on 22 Modules of Geneva Barrel SCT Full Length Prototype (Semitek AT series: 10kW @ 25 C)

NTC SMD resistors (Taiyo Yuden & Semitec) irradiated to 1.2 x 10 ¹⁵ p (25 GeV/c) /cm². Dispersion pre&post irradiation ~ 0.3K, (< 0.5 K OK)

I-Box Hysteresis

In PIXELS, interlock set ("POWER DISABLE") @ 0.15°C and reset ("POWER RE-ENABLE") @ -0.79°C. Tested extensively with deliberate liquid runouts Hard-wired T_{switch} of 2 comparators by fixed resistor network.

Typical Screen from Bridgeview User Interface Taken in I-Box Hysteresis Studies



I-box channel status

Module Temperature Transients Provoked by Deliberate liquid run-out kept within acceptable limits (not exceeding +2 C) by I-Boxes

The I-Box and Thermal Runaway Prevention

- Silicon Detectors must be kept near -7 C.
- I_{leak} and V_{dep} increase with irradiation over the lifetime of the detector. I_{leak} strongly temperature dependent and can cause a positive feedback runaway with T.

Low mass Requirement on cooling system →→ LOW <u>THERMAL</u> MASS !!

At dissipation around 6 Watts/ detector tile, heat-up rates > 5 C sec⁻¹ on Si, <u>Evaporative OR Monophase liquid cooling!!!</u>

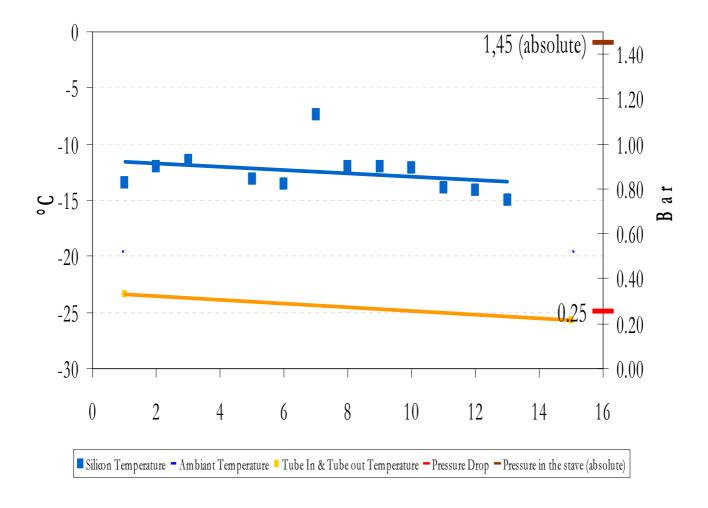
→ Need fast, HARD-WIRED interlocks (DIGITAL) between temperature sensors on individual Si detectors & their individual multi-rail power supply channels (> 6000 in SCT & Pixel systems)

 → Action MUST NOT depend on volatile SCADA software (PVSS2).
 (FPGA OK if on redundant, cascaded UPS, together with T Sensors &Discriminators)

Pixel Stave Re-Baselining Qualification Stave thermal conduction test (November stave, After the Temperature cycles)

The Si temperature average is -12.96 °C on the tilted Si, and -7.34°C on the middle Si. The Pressure drop along the stave is 0.2 Bar.

Thermal conduction after Thermal and pressure cycles (Power dissipated 134W)



Flow and Pressure Control in the Evaporative Cooling System and Analog Pneumatic Controls Development

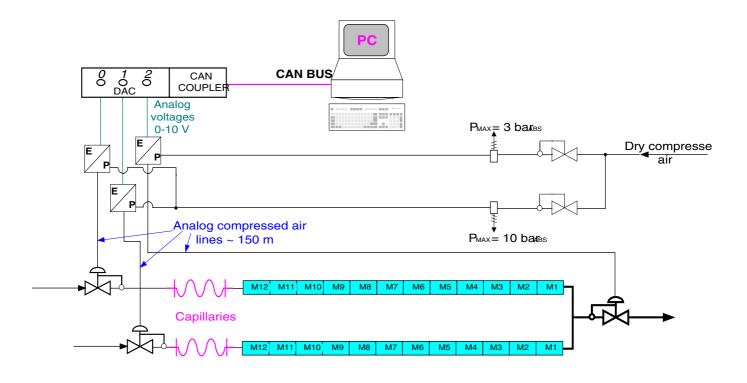
EVAPORATIVE SYSTEM OPERATION

- Liquid refrigerant passes through injector / capillary at a mass low rate dependent on the liquid pressure upstream of the injector
- Liquid refrigerant evaporates in the on-detector cooling channels with attached silicon detectors
- Pressure in channel ==> evaporating temperature ==> <u>silicon detector temperature</u>
- <u>CONTROL PRINCIPLE</u>

(Comparison vs. Liquid):

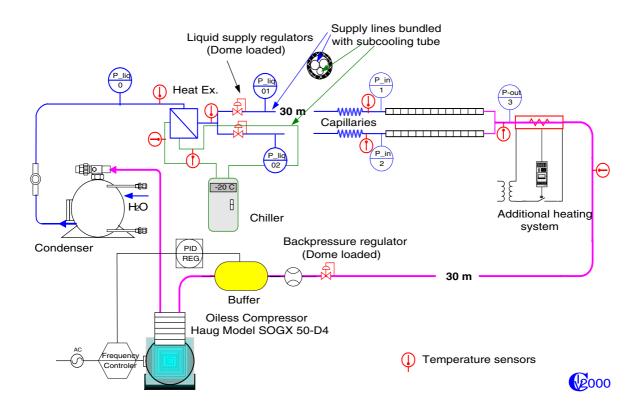
- Two Variable parameters
 - (1) Mass Flow Rate:
 - pressure upstream of injector
 - (via analog pneumatic-piloted regulator) ==> (vs. pressure at start of liquid circuit)
 - (2) Evaporating Temperature
 - pressure in on detector cooling channel
 - (via analog pneumatic-piloted back-pressure regulator) ==>
 (vs. temperature of liquid delivery) INDIVIDUAL CIRCUIT TEMPERATURES NOT POSSIBLE IN PARALLEL LIQUID SYSTEM WITH SINGLE SUPPLY TEMEPERATURE

Prototype Electro-Pneumatic Control Scheme



Schematic of Prototype C₃F₈ Evaporative Recirculator

Prototype Circulator and Control System



FLOW VARIATION STUDIES

(1) FLOW VARIATION VIA INTERLOCK "ON" BIT COUNTING

DAC ➡ E2P ➡ Dome Loaded Regulator Pressure Upstream of Capillary ➡ Flow

PROTOCOL

 $P_{CAPILLARY} = P_{SL(Tin)} + m * # (powered modules)$

 $\begin{array}{ll} \mbox{Where: } P_{SL(Tin)} \mbox{ is the saturated liquid pressure} \\ \mbox{ at the } C_3 F_8 \mbox{ injection temperature (see cycle)} \\ \mbox{ m is incremental pressure (mbar)} \\ \mbox{ to remove heat of one Si module (~ 10 Watts)} \end{array}$

PROTOCOL DEMONSTRATED TO WORK: (Temperatures on remaining powered modules and exhaust stable with varying flow/load)

HOWEVER: need first to *accurately* find m via; (P_{CAPILLARY(22 Modules)} - P_{SL(Tin)})/22

ALSO, PROTOCOL sensitive to variable module power unless modified...

 $\mathbf{P}_{\text{CAPILLARY}} = \mathbf{P}_{\text{SL}(\text{Tin})} + \mathbf{m}' * \Sigma_{i}(\text{POWER}_{\text{module}(i)})$

m is normalized pressure/power factor (mbar/W),

BUT...would need <u>continuous</u> V,I data for each module from DCS & Power Supplies: clumsy

Installed Test Structures and DAQ/Control System

Present status of the installation in the lab - part two



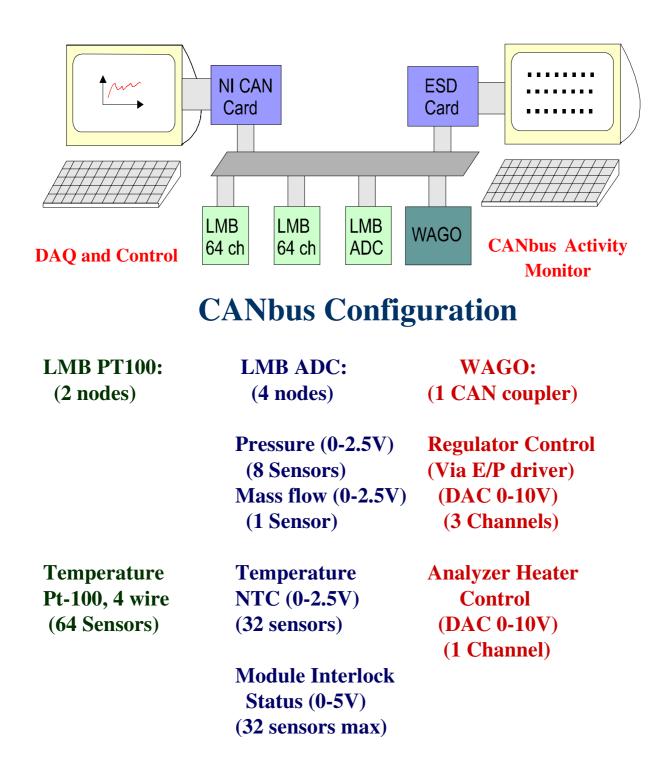
LMB and WAGO based CanBus DAQ System that enables monitoring of the temperatures and basic control parameters of the Cooling system



2 SCT thermal model staves and 2 "parallel ghost" SCT staves placed in the temperature controlled box



CAN-bus & LMB based measurement system

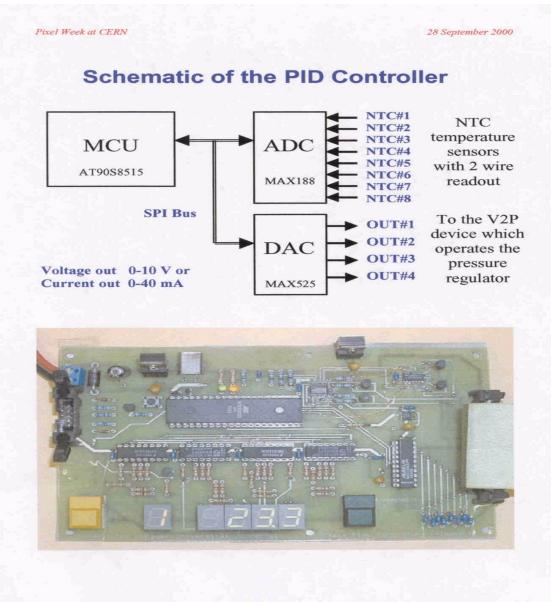


THE SOLUTION...

C₃F₈ proportional flow regulation to maintain Temperature

(NTC sensor) at exhaust above T_{evap} for varying (analog) load (Independent of module power variations)

Single Chip PID For Coolant Flow Control (On ATMEL RISC μ Controller [C \rightarrow Gnu])



University of Wuppertal

Functional description of the PID controller

- There can be up to 4 independent PID controllers in our prototype hardware.
- Each PID uses 2 temperature sensors: 1 main sensor [outlet tube, usually after the heater] and 1 security sensor [end of stave tubing].

Sample rate 4 Hz

 $Out_P = P * (Temp - Setpoint)$ $Out_I = I * Accumulated_Error$ $Out_D = D * (Error - Last_Error)$

 $Out = Out_P + Out_I + Out_D$

The temperature of the security sensor is monitored and if its value is above a defined critical temperature

Temp_{crit} = Temp_{evap} + Δ Temp, Δ Temp \in (2-3 K)

the PID mode is disabled. In this case a constant mass flow, capable of cooling the full staves power is used.

University of Wuppertal

All Hardware Elements of Cooling Control System Satisfactorily Demonstrated

- Hard-wired Power Interlock & NTC sensors
- $\begin{array}{ll} & \textbf{PID algorithm in ATMEL RISC } \mu \\ & \rightarrow \textbf{DAC} \end{array}$

 \rightarrow V2P

→ Analog Air-loaded regulator for coolant flow control

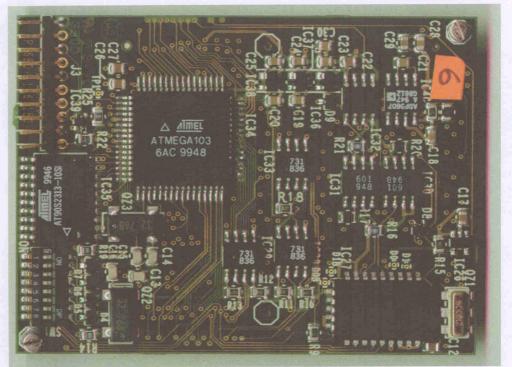
 Powered modules and exhaust stable (in spec. ranges) during (1-22 module switching) transients and exhaust tube temperature maintained several degrees above evaporation temperature, indicating liquid run out maintained just beyond end of structure.

† Implications for Services

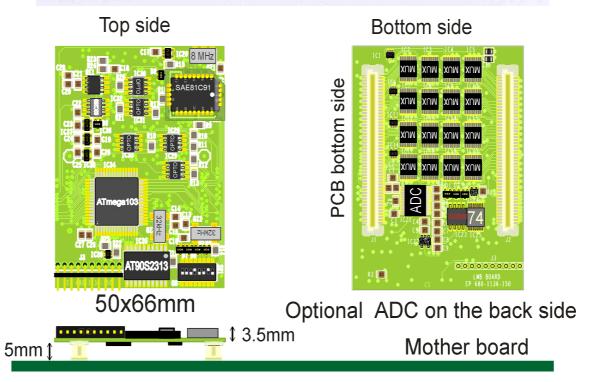
- With Flow regulation, unnecessary to directly heat individual exhaust tubes;
- With precooling of entry C₃F₈ liquid, very low power required (ONLY!) on active insulation per circuit exhaust (~ 40W on 2 meters length, 5 mm Armaflex)
- Input Liquid Tubing Probably may not require active insulation with $T_{precool} \sim -15 \ ^{\circ}C(to \ test)$.

FUTURE STUDIES Integrate the PID algorithm on new E-LMB, with new Development of Add-on DAC

Same ATMEL Family µController in ATLAS DCS (E-Local Monitor Board)

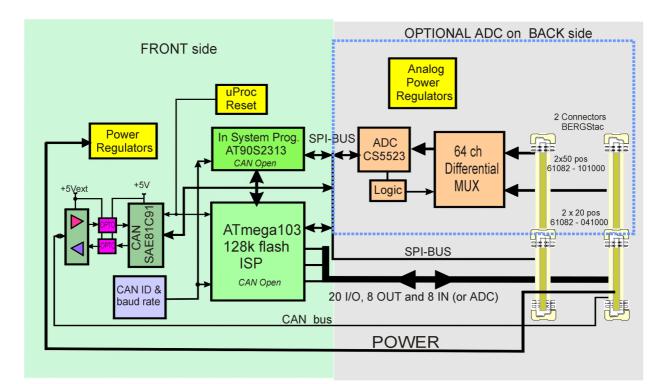


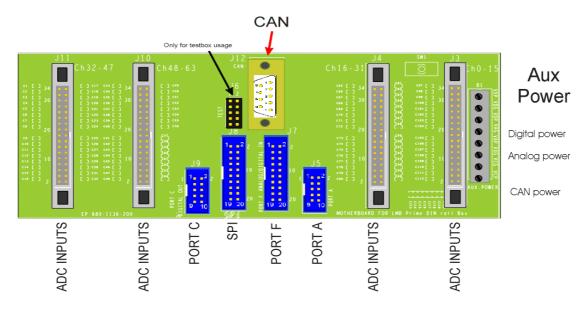
Front side of Embedded Local Monitor Board ELMB Size 50x66 mm October 2000 version



ATLAS E-LMB Block Diagram, Shows ATMEL 128K RISC μController, SPI ports for connection to external DAC cards (NIKHEF)

(µcontroller allows flow control implementation using either smart (PID) algorithm, or else transparent (DAC only))





Draft Specification for External E-LMB DAC

(1) Number of DACs per SPI port:

(2) DAC Bits Precision :

- * This precision sufficient for the pixel & SCT cooling controls (analog flow & evaporation pressure setting), but may be insufficient for other (as yet undefined) uses/users.
- (3) E-LMB Connection Path:
- (4) DAC Analog Output type:
- (5) DAC Output connector:
- (6) Power Supply Rails:

Preference Compatibility with SPI-PORT (J8) on E-LMB motherboard viz: + 5V analog, -5V analog, analog ground + 5V digital, digital ground

(7) Power Supply Connects:

Preferred via J8 (E-LMB motherboard SPI-PORT)

(8) Local Memory:

For 4 digital words (10 bit eqv.): one / DAC channel

(9) Time between local memory refresh:

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8-pin DIL ribbon (unshielded)

SPI-PORT of

4-20 mA

As E-LMB/ motherboard

E-LMB motherboard

0.1 seconds minimum

10*

4

18

Baseline Evaporative Circulator System

In Personnel Accessible Area (USA 15)

- Remote, Hermetic, Oil-less compressors
- Local PID controllers regulating: aspiration pressure (compressor speed control) condenser pressure (chilled water flow rate)

Six such compressor sets:

Advantage of compressor parallelism: allows prior use in assembly sites.

In Personnel Inaccessible area UX15 (high B, radiation fields)

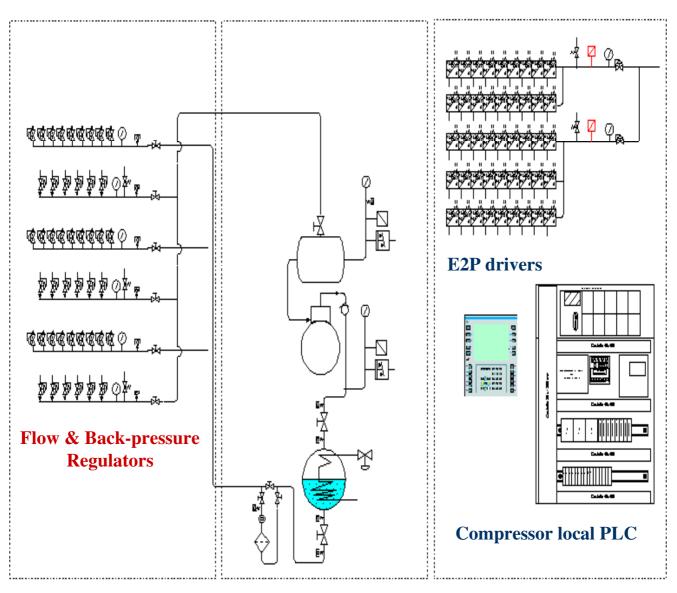
Dome Loaded Pressure Regulators for:

Delivery of Sub-Cooled Liquid to each circuit (Linear Flow regulation between Condenser Pressure and Saturated Liquid Line)

Operating temperature on each circuit, control of boiling pressure (variable to accommodate Si radiation damage).

Active Insulation on Critical Parts of Coolant Delivery and Exhaust Tubing

Placement of Recirculator Control Components in Final ATLAS Installation



Regulators on ATLAS Service Platforms

Compressor, Condenser , Compressor local PLC & E2P drivers in USA15 Technical Cavern

LMB (and I-Box) Channel Count for Pixel Modules

(1) **B-Layer**

NTCs for Module Count: 12*13*2 = 312: CORRESPONDING 64 Chan LMBs = 4.875 I-Box Channel Count: 12*13*2 = 312: Analog In Channel Count: 12*13*2 = 312 (I-Bit Status) CORRESPONDING 64 Chan LMBs = 4.875

(2) Layer 1,2

NTCs for Module Count: 48*13*2 = 1248: CORRESPONDING 64 Chan LMBs = 19.5 I-Box Channel Count: 48*13*2 = 1248: Analog In Channel Count: 48*13*2 = 1248 (I-Bit Status) CORRESPONDING 64 Chan LMBs = 19.5

(3) Disks (Guess)

NTCs for Module Count: 26*6*4 = 624: CORRESPONDING 64 Chan LMBs = 9.75 I-Box Channel Count: 26*6*4 = 624: Analog In Channel Count: 26*6*4 = 624 (I-Bit Status) CORRESPONDING 64 Chan LMBs = 9.75

> 64 Chan LMBs (Modules Only) = 34.125 Additional 64 Chan LMBs (I-bits) = 34.125

THEREFORE COUNT I-BITS FOR FREE IN P/S?

LMB Channel Count for Pixel Coolant Monitor & Control

(1) **B-Layer (Example Breakdown)**

12 circuits of 2 staves in series: 12 inputs, 12 outputs

NTCS on/near on-detector structure per circuit (1/E-LMB analog input) (1) Input, stave tube 1 Output, stave tube 1 or Input, stave tube 2 (2) (3) **Output, stave tube 2 exhaust (control function) Output, stave tube 2 exhaust (reserve sensor for control function)** (4) (5) **Exhaust Remote (control function) Exhaust Remote (reserve sensor for control function)** (6) **Pressure measurement (upstream of capillary)** (7) (8) **Pressure measurement (exhaust) SUBTOTAL:** 72 NTC sensors/ Analog Inputs **PID DACs in LMB µcontrollers for flow control:** (1/E-LMB analog output channel): 12 DACs in LMB ucontrollers for boiling pressure control: (1/E-LMB analog output channel): 12 LMBs 1.125 (Analog Input Channels Only): 1.125

LMBs for DAC (@4 DAC/E-LMB):

6

LMB Channel Count for Pixel Coolant Monitor & Control

(2) Layers 1,2 (Example Breakdown)

48 circuits of 2 staves in series: 48 inputs, 48 outputs

NTCS on/near on-detector structure per circuit (1/E-LMB analog input) (1) Input, stave tube 1 Output, stave tube 1 or Input, stave tube 2 (2) (3) **Output, stave tube 2 exhaust (control function) Output, stave tube 2 exhaust (reserve sensor for control function)** (4) (5) **Exhaust Remote (control function) Exhaust Remote (reserve sensor for control function)** (6) (7) **Pressure measurement (upstream of capillary)** (8) **Pressure measurement (exhaust) SUBTOTAL: 368 NTC sensors/ Analog Inputs PID DACs in LMB µcontrollers for flow control:** (1/E-LMB analog output channel): **48** DACs in LMB ucontrollers for boiling pressure control: (1/E-LMB analog output channel): **48** LMBs 1.125 (Analog Input Channels Only): 5.75

LMBs for DAC (@4 DAC/E-LMB):

24

LMB Channel Count for Pixel Coolant Monitor & Control

(3) Disks (Example Breakdown)

26 circuits of multisectors in series: 26 inputs, 26 outputs

NTCS on/near on-detector structure per circuit (1/E-LMB analog input) (1) Input, stave tube 1

- (2) Output, stave tube 1 or Input, stave tube 2
- (3) **Output, stave tube 2 exhaust (control function)**
- (4) Output, stave tube 2 exhaust (reserve sensor for control function)
- (5) Exhaust Remote (control function)
- (6) Exhaust Remote (reserve sensor for control function)
- (7) **Pressure measurement (upstream of capillary)**
- (8) Pressure measurement (exhaust) SUBTOTAL: 208 NTC sensors/ Analog Inputs

PID DACs in LMB μcontrollers for flow control:
(1/E-LMB analog output channel):26DACs in LMB μcontrollers for boiling pressure control:
(1/E-LMB analog output channel):26

LMBs 1.125 (Analog Input Channels Only):3.25LMBs for DAC (@4 DAC/E-LMB):13

LMB Channel Count for Pixel Tube Bundle External Temperature Control

Assumption:

Each bundle has active insulation over ~30 m between PPB3 & PPB1, which is divided into 3 zones as follows :

(1) PPB1 to end of ID volume
(2) End of ID volume to PPB2
(3) PPB2 to PPB3

Each zone of each bundle has 4 temperature sensors : 2 for monitoring and 2 for control:

Two require PID activity to control the active insulation heaters.

Surface	Input Bundles / End	Output Bundles /End	Totals (Both Ends)
B layer	4(3 tubes)	4(3 tubes)	8 (3 tubes)
1,2	4(6 tubes)	8(3 tubes)	24
Disks	1(6 tubes)	3(3 tubes)	
	1(7 tubes)	1(4 tubes)	12
Total No bundles (Both ends):			44
No Zones (44*3) :			132
	No Sens	ors (44*3*4) :	528
	8.25		
	132		
	33		

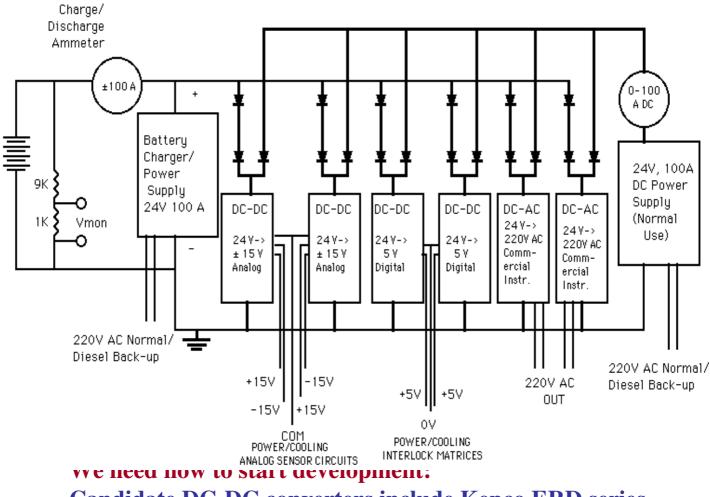
TOTAL E-LMB REQUIREMENT (SET& SUBSET): (MODULES+CIRCUIT CONTROL+TUBE BUNDLES) 52.5 (INPUTS, NOT INCLUDING I-Bits, 76 for DAC/PID DAC)

CONCLUDE:

NEED 8 PID DACs PER E-LMB, OR REDUCE # BUNDLE ZONES)

Highly Redundant UPS for I-Box Power

- Most Commercial UPS gives 120/220V, generated by DC-AC conversion, OK for servers etc...
 - Protects against primary AC failure and lightning etc but does not protect against downstream AC-DC supply failure.
- It is preferable to have the redundancy as close as possible to the protected load: i.e. at the LVDC level

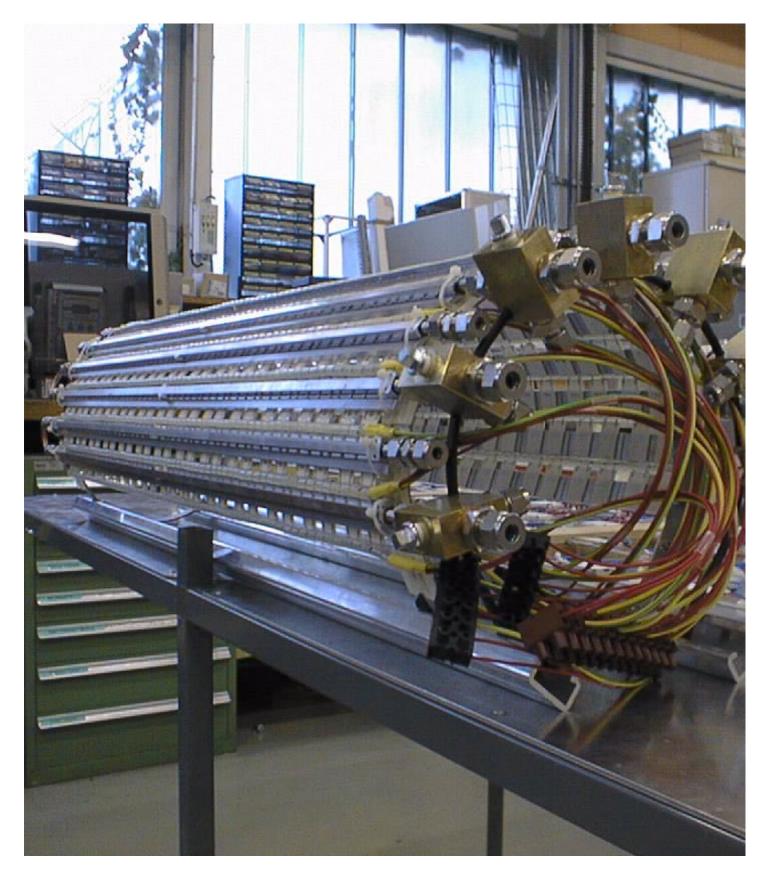


Candidate DC-DC converters include Kepco ERD series.

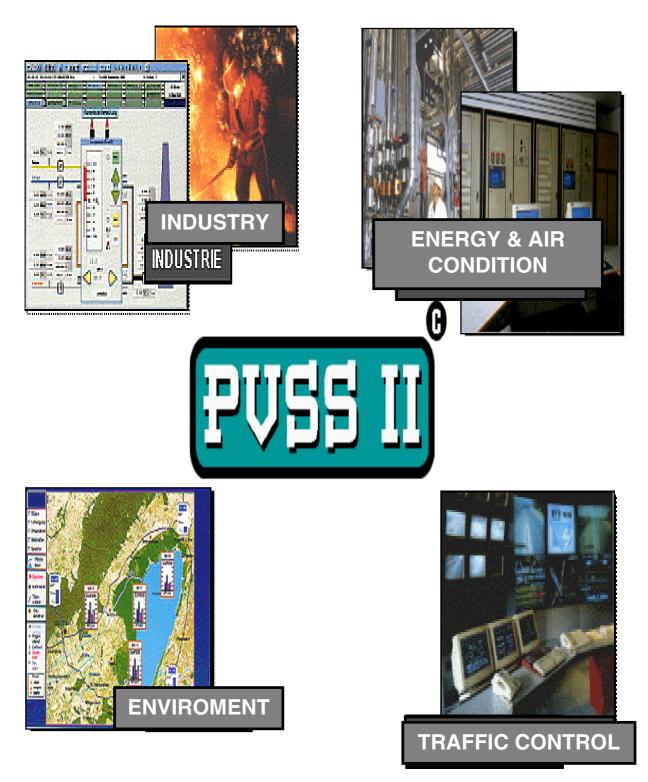
Modularity of Circuits and Analog Flow Elements in ATLAS SCT & Pixel Evaporative Cooling Demonstrator.

Layer	Circuits	Supply Capillaries / Circuit	Power/ (Output) circuit (W)	Flow regs	Boiling Pr. Regs
SCT 4	2	2	480	4	2
SCT 3	2	2	480	4	2
SCT 2	2	1	480	2	1
SCT 1	2	1	480	2	1
Pixel 2	3	1	208	3	3
Pixel 1	2	1	208	2	2
B layer	1	1	288	1	1
SCT disk/4	1	3	330	3	1
Pixel disk/6	1	1	96	1	1
TOTALS			4218	22	14
TOTAL FOR SCT 4			6720	28	14

Dummy Pixel Staves for Cooling Demonstrator

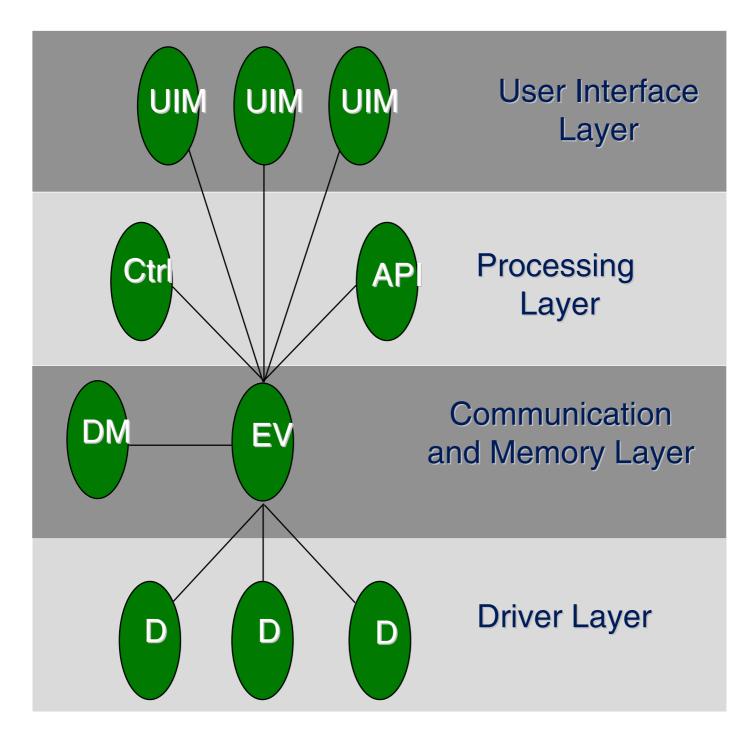


ATLAS SCADA: PVSS2. Chosen 9/2000 Until 6/2001 for Evaluation/Final Decision: Range of Application



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PVSS II Manager Overview



System management / user admin.

🚯 Vision_9: system management						
<u>File Panel ?</u>						and the second sec
e i E C	PVSS: User Administration					
Authorizations Drivers	User name	Group		ID		Users:
	root para	root para		0	de_AT.iso88591 de_AT.iso88591	Add user Change user
	operatorAll operator	operatorAll operator		0 0	de_AT.iso88591 de_AT.iso88591	Delete user
user sy: administration aut	guest gast	guest guest		0 1	de_AT.iso88591 de_AT.iso88591	Groups & authorization:
	demo	guest		2	en_GB.iso88591	Group administration Authorization levels
current user: root	1-11 12-22 23-32 Authorization levels:		Independent o	of the v	vorkstation:	Workstation authorization
	년 1 년 2		□1 □2			
	⊠ 3 ⊠ 4		□ 3 □4			
	⊠ 5		E 5			
	☑ 6 ☑ 7		⊑6 ⊑7			
	E 8 E 9		□ 8 □ 9			
	☑ 10 ☑ 11		⊑ 10 ⊑ 11			Help
						Close

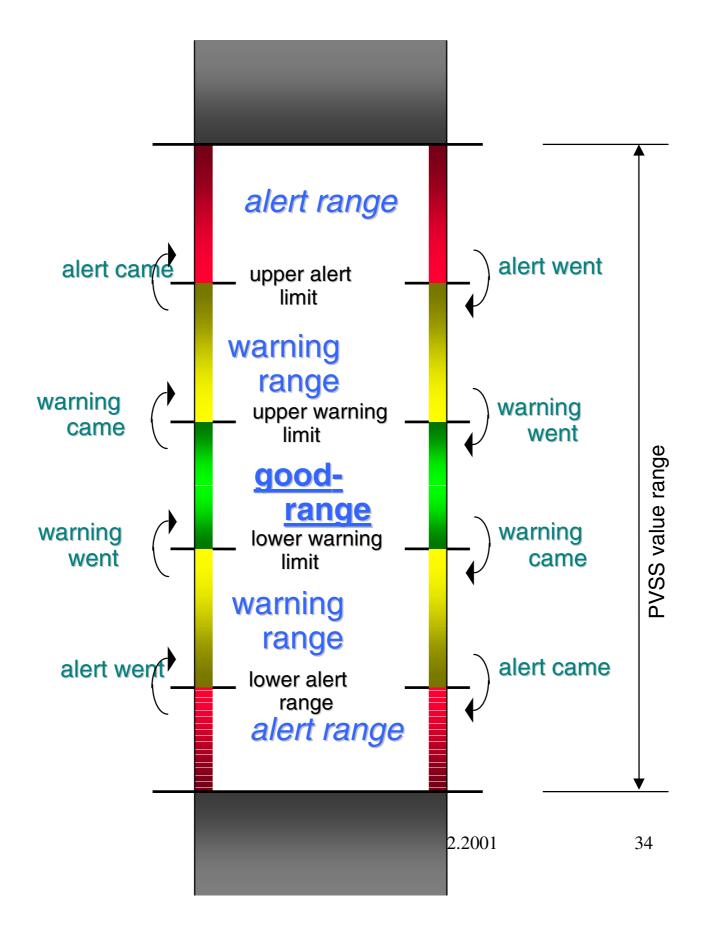


	DP-Parameterization		
Vision_1: data point paramet File Panel ?	Alert class DPE: System1:valve1_1.response.malfunction		
filter options:	Alert parameters Arguments		
dp-filter:	priority:		
tirest ExampleDP_Text in the state of the	Save alerts		
valve1_1 Common lock r defaults	acknowl. type: Pair of alerts must be acknowledged		
response common E common	Alert status — Alert color — Alerting		
	no alert Original color V		
⊡	CAME/dilacknowl. [0,80,100]		
eler <u>class</u>	WENT/unacknowl. <[0,60,0],3,Weiss,3,[100,100,10]		
⊡⊡≣ lock ⊡-⊡ valve2_1 ⊡-⊡ valve1_2	K/G/unacknowl.		
in in the second secon	OK Cancel Apply Help		

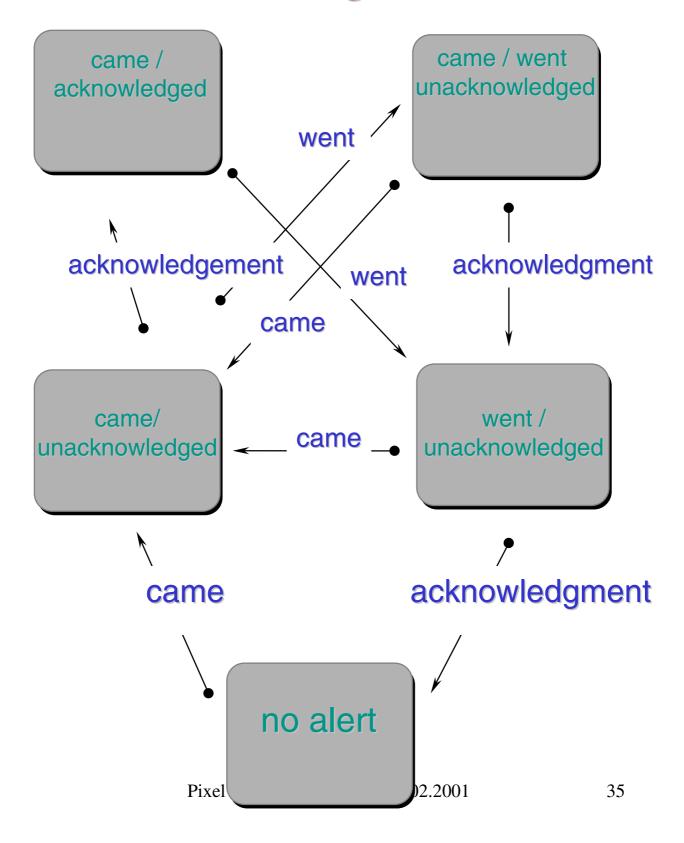
PVSS II Uses C-like Scripts to Link DataPoints (eg analog inputs like T, P) to communicate with DB, reactions: Example for a Ctrl-Function

```
workCB (string dp, int x, int y)
{
    int z;
    z = x + y;
    dpSet(dp, z); /* writes the value
    of "z" to the data-point "dp" */
}
```

Definitions



PVSS II "Came" and "Went Alarms Require and Log Acknowledgements



DCS DAQ Electronics Status

- First pre-production E-LMBs delivered
 (In pixels, CERN, Wuppertal have taken delivery)
- Small E-LMB test system running with PVSS II SCADA software in cooling lab
- Requested 25 E-LMBs (delivery Spring '01) for Evaporative Cooling Demonstrator and Cooling System at SCT assembly site #1 (Oxford, late '01)
- Scalable PVSS2 with E-LMB system to be developed for Evaporative Cooling Demonstrator (2 students, end Feb + V. Filimonov for 2 months)
- Need to speed Add-On DAC development for E-LMB SPI Bus (Wuppertal/ NIKHEF) Convergence to common ATLAS spec has started
- Experience has shown Cooling Developments are best motor for controls/ DCS DAQ development:
- PVSS2+E-LMBs at Local Site when pixel cooling tests shift from CERN?? (Much to do...)

SOME FAULT RESPONSE ACTIONS

FROM SAFETY ANALYSIS REPORT JUNE 2000, CONTACT: G. BENINCASA

(1) Global LVDC power failure

Need to protect structures from excessive cold at 0 power.
 → Taken care of within a few seconds by analog flow regulation scheme on the basis of sensed exhaust temperature. (See later in talk)

(2) Isolation of a Cooling Circuit

Prevent excessive pressure building up in inactive circuit containing C₃F₈ liquid valves/regulators.

→ First close C₃F₈ liquid supply regulator (Analog compressed air signal #1 via I→P to Saturated Liquid Pressure or below)

NOTE: Exhaust back-pressure regulator NOT a shut-off device: → → will regulate C₃F₈ boiling pressure to its dome load pressure (analog compressed air signal #2 via I→P)

(3) Turn-on to correct boiling pressure.

Compressor Aspiration Tank pre-filled to preferred pressure (P_{tank} > P_{evap}) with superheated C₃F₈ vapor (via flash evaporation from liquid delivery), for start of pressure ramp dow → → then reduced at required speed (analog air signal #2 to back-pressure regulator)

(4) DACs, I→P Regulators MUST be on Cascaded Redundant UPS.